14.2 mm One Digit Display SMD

(Common Anode type)

Features

- 14.2 mm One Digit Display
- Long lifetime operation
- IC compatible
- Low power dissipation
- · Gray surface & white segment or dot
- RoHS compliant

Applications

- Counting device
- Clock

Absolute Maximum Rating (Ta=25 °C)

		Value	Unit	
Item	Symbol	Red/Yellow/Yellow Green		
DC Forward Current	lF	25	mA	
Pulse Forward Current#	IFP	80	mA	
Reverse Voltage	VR	5	V	
Power Dissipation	Pt	65	mW	
Operating Temperature	Topr	-30 ~ +85	°C	
Storage Temperature	Tstg	-40 ~ +100	°C	
Lead Soldering Temperature (1.6 mm Below body)	Tsol	260 °C/3 sec	0°	

#Pulse width Max.10 ms Duty ratio max 1/10 #Reflow time Max 3 seconds

Electrical -Optical Characteristics (Ta=25 °C)

		VF (V)		lR(μA)	lv(mcd)		λD(nm)						
BN	Color		Min.	Тур.	Max.	Max.	Min.	Тур.	Max.	Min.	Тур.	Max.	
			IF=20mA		VR=5V	IF=10mA		IF=20mA					
2903157	Red	R		-	2.1	2.6	100	5	13	25	625	630	640
2903158	Yellow	Y		-	2.1	2.6	100	8	16	25	585	590	595
2903159	Yellow Green	YG		-	2.1	2.6	100	5	13	20	565	570	575

*1 Tolerance of measurements of chromaticity coordinate is +10 %

*2 Tolerance of measurements of dominant wavelength is ± 1 nm

*3 Tolerance of measurements of luminous intensity is +15 %

*4 Tolerance of measurements of forward voltage is ± 0.1 V



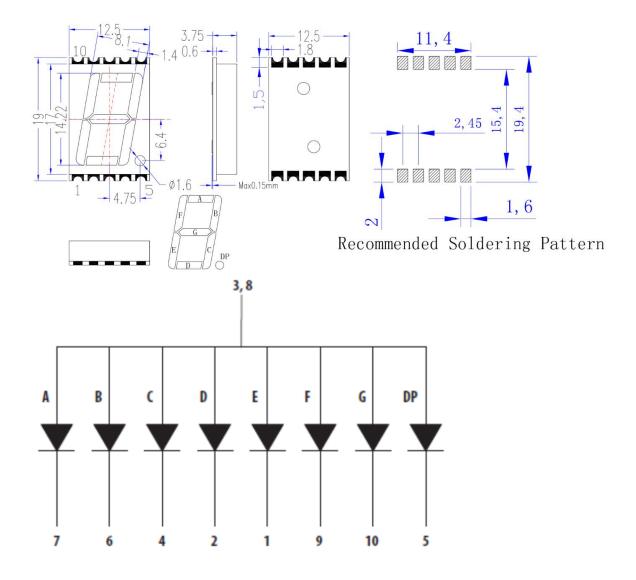




Package Dimensions

Common Anode type

Note: 1, Unit: mm (Tolerance: <u>+</u>0.25 mm unless otherwise noted)

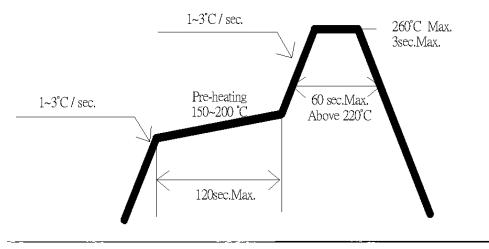




Soldering Conditions

Reflow Soldering		Hand Soldering			
Pre-Heat	150 ~ 200 °C				
Pre-Heat Time	120 sec. Max.		350 °C Max.		
Peak temperature	260 °C Max.	Temperature Soldering time	3 sec. Max. (one time only)		
Dipping Time	3 sec. Max.				
Condition	Refer to Temperature-profile		(

Reflow Soldering Condition (Lead-free Solder)



· Recommended soldering conditions vary according to the type of LED

• Although the recommended soldering conditions are specified in the above table, reflow, or hand soldering at the lowest possible temperature is desirable for the LEDs.

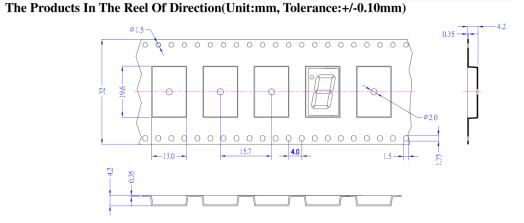
- A rapid-rate process is not recommended for cooling the LEDs down from the peak temperature.
- All SMD LED products are pb-free soldering available.

• Occasionally there is a brightness decrease caused by the influence of heat or ambient atmosphere during air reflow. It is recommended that the User use the nitrogen reflow method.

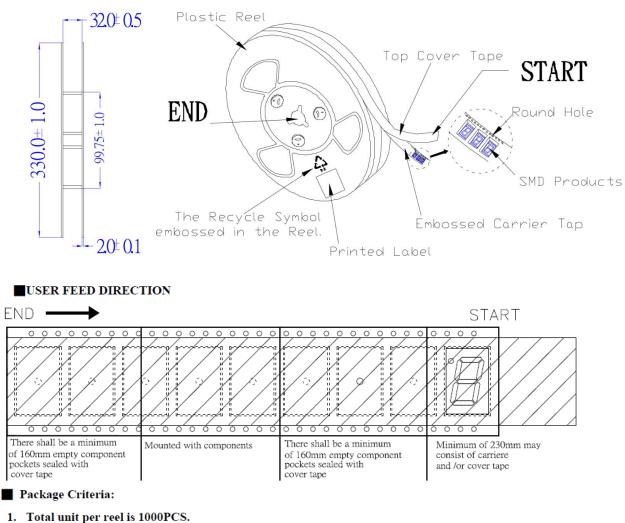
• Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable a doublehead soldering iron should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.

- · Reflow soldering should not be done more than two times.
- When soldering, do not put stress on the LEDs during heating.
- After soldering, do not warp the circuit board.





■ Label Direction & Content In The Roll(Unit:mm)



Max 5 reels/5000PCS are packaged in each carton



	CAUTION This bag contains OISTURE-SENSITIVE DEVICES ife in sealed bag: 12 months at <40 °C a	LEVEL 3
relative humidity (I		
2. Peak package bo	dy temperature: Per product label	
or other high tem	ed, devices that will be subjected to reflow perature process must be 168 hours of factory conditions ≤30 °C/60%F D-033	
•	ake, before mounting, if: or Card is >10% when read at 23±5 °C	
5. If baking is requir	ed, devices may be baked for 20 hours a	t 60±5 °C
Bag Seal Date:		
-	If Blank, see adjacent bar code label berature defined by IPC/JEDEC J-STD-020	